

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L57	281038	trace	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/20 15:53
L60	12223	(wafer substrate) with ((chip die semiconductor IC (intergrated near circuit)) near3 array)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/20 14:37
L61	1839	57 and 60	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/20 14:37
L62	1777	61 and (@ad<"20030806" @rlad<"20030806")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/20 15:53
L63	65977	(conduct\$3 metal\$4) near line	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/20 15:53
L64	1139	60 and 63	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/20 15:53
L65	1090	64 and (@ad<"20030806" @rlad<"20030806")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/20 15:53
L66	891	65 not 62	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/20 15:54

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L57	281038	trace	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/20 14:36
L60	12223	(wafer substrate) with ((chip die semiconductor IC (intergrated near circuit)) near3 array)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/20 14:37
L61	1839	57 and 60	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/20 14:37
L62	1777	61 and (@ad<"20030806" @rlad<"20030806")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/20 14:37

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L18	2195678	substrate wafer	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/20 11:29
L19	242137	array with (chip component element semiconductor (intergrated near circuit))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/20 11:29
L21	551	straight near2 trace	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/20 11:30
L22	37	18 and 19 and 21	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/06/20 11:30